

## Magnetic Sensor series

# 3-Axis Digital Magnetometer IC

## BM1422GMV

### General Description

BM1422GMV is a 3-axis magnetic sensor which incorporates magneto-impedance (MI) elements to detect magnetic field and a control IC in a small package.

### Features

- 3-axis Magnetic Sensor using MI Elements
- I<sup>2</sup>C Interface
- 12bit / 14bit Digital Output
- Selectable I<sup>2</sup>C Slave Address  
( ADDR=L: 0001110, ADDR=H: 0001111 )

### Applications

- Wristwatch
- Mobile phone, Smartphone

### Key Specifications

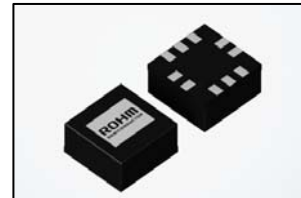
- Input Voltage Range (AVDD): 1.7V to 2.0V
- Input Voltage Range (DVDD): 1.7V to 2.0V
- Operating Current (100SPS): 0.15mA(Typ)
- Magnetic Measurable Range: ±1200μT(Typ)
- Magnetic Sensitivity: 0.042μT/LSB(Typ)
- Maximum Exposed Field: 1000mT
- Operating Temperature Range: -40°C to +85°C

### Package

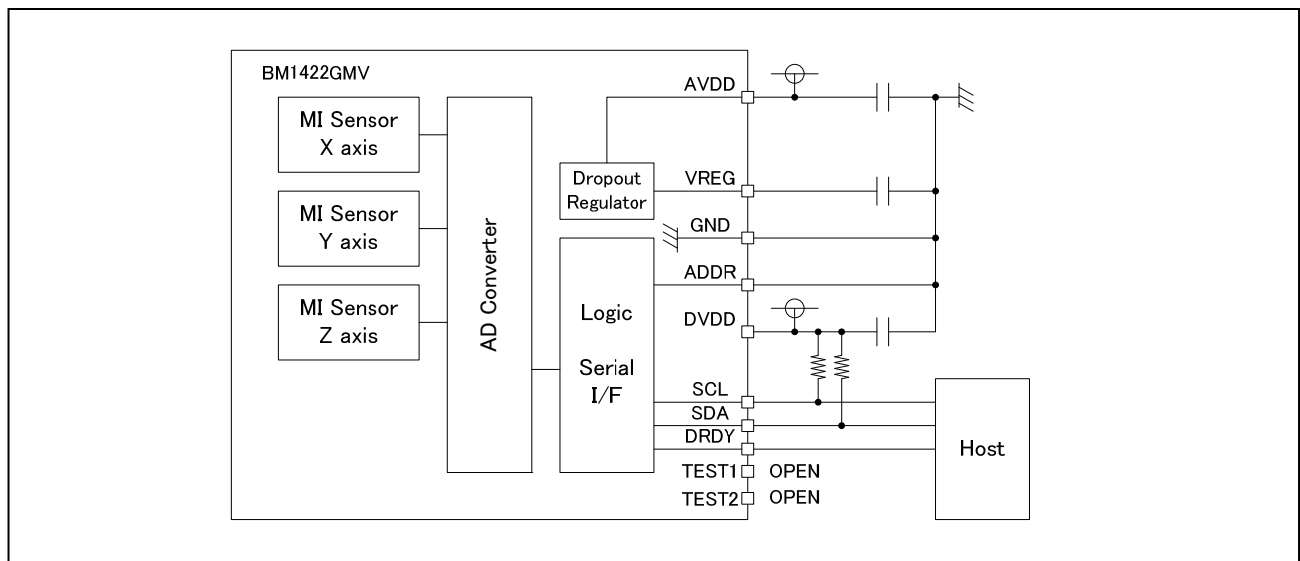
MLGA010V020A

W(Typ) x D(Typ) x H(Max)

2.00mm x 2.00mm x 1.00mm



### Typical Application Circuit


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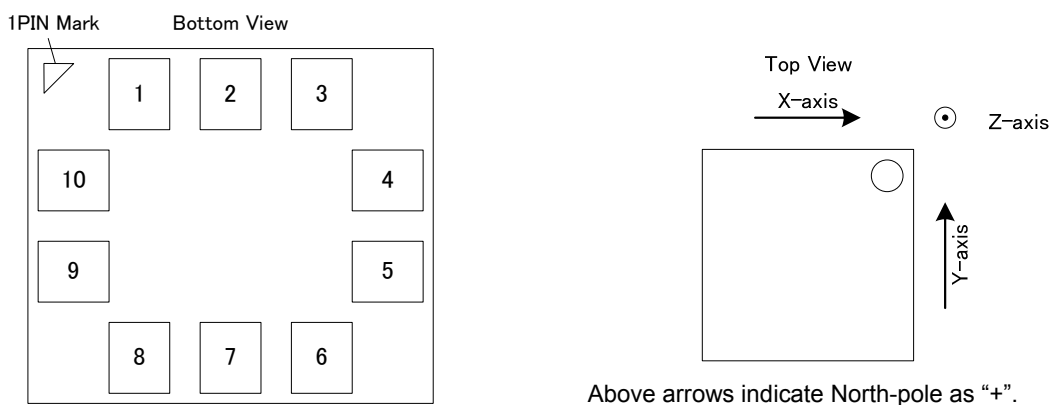
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## Pin Configuration



## Pin Description

Pin No.	Pin Name	Function
1	AVDD	Analog circuit power supply <sup>(Note 1)</sup>
2	GND	Ground
3	VREG	Internal regulator output <sup>(Note 2)</sup>
4	TEST1	Test pin <sup>(Note 3)</sup>
5	SDA	I <sup>2</sup> C signal data I/O
6	TEST2	Test pin <sup>(Note 3)</sup>
7	SCL	I <sup>2</sup> C signal clock input
8	DRDY	Data ready output pin
9	ADDR	I <sup>2</sup> C programmable address bit <sup>(Note 4)</sup>
10	DVDD	Digital circuit power supply <sup>(Note 5)</sup>

(Note 1) Please place a bypass capacitor between AVDD and GND in the proximity of the terminals.

(Note 2) Please place a bypass capacitor between VREG and GND in the proximity of the terminals.

Please set a bypass capacitor of 1.0uF between VREG and GND

(Note 3) Use as Non-Connection (NC).

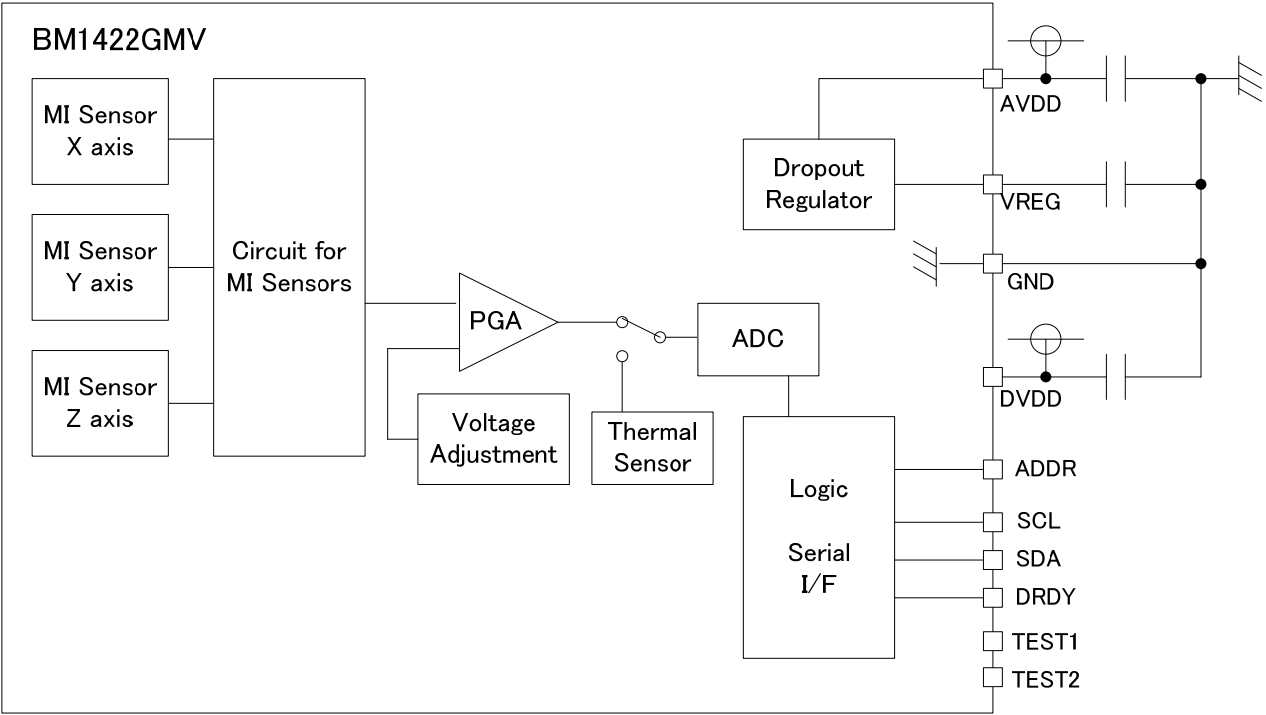
(Note 4) Please connect to DVDD or GND.

(Note 5) Please place a bypass capacitor between DVDD and GND in the proximity of the terminals.

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Block Diagram



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**Absolute Maximum Ratings (Ta = 25°C)**

Parameter	Symbol	Rating	Unit
Supply Voltage (AVDD)	Vdd_a	0 to +4.5	V
Supply Voltage (DVDD)	Vdd_d	0 to +4.5	V
Input Voltage	Vin	-0.3 to +(Vdd_d+0.3)	V
Operating Temperature Range	Topr	-40 to +85	°C
Storage Temperature Range	Tstg	-40 to +125	°C
Maximum Exposed Field	Mef	-1000 to +1000	mT
Power Dissipation	Pd	0.52 <sup>(Note 1)</sup>	W

(Note 1) Derating is done 5.2 mW/°C for operating above Ta ≥ 25°C (Mount on 4-layer 114.3mm x 76.2mm x 1.6mm board)

**Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

**Recommended Operating Conditions (Ta= -40°C to +85°C)**

Parameter	Symbol	Rating	Unit
Supply Voltage (AVDD)	Vdd_a	+1.7 to +2.0	V
Supply Voltage (DVDD)	Vdd_d	+1.7 to +2.0	V
I <sup>2</sup> C Clock Frequency	fSCL	MAX 400	kHz

**Electrical Characteristics (Unless otherwise specified AVDD=1.8V, DVDD=1.8V, GND=0.0V, Ta=25°C)**

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
<b>Current Consumption</b>						
Average Current during Measurement	Idd	-	150	300	μA	Output Data Rate = 100SPS
Stand-by-mode Current	Iss	-	1.5	5	μA	ALL Power Down
<b>Logic</b>						
Low-level Input Voltage	V <sub>IL</sub>	GND	-	0.3 * DVDD	V	
High-level Input Voltage	V <sub>IH</sub>	0.7 * DVDD	-	DVDD	V	
Low-level Input Current	I <sub>IL</sub>	-10	-	0	μA	V <sub>IL</sub> = GND
High-level Input Current	I <sub>IH</sub>	0	-	10	μA	V <sub>IH</sub> = DVDD
Low-level Output Voltage	V <sub>OL</sub>	GND	-	0.2 * DVDD	V	IL = -0.3mA
High-level Output Voltage	V <sub>OH</sub>	0.8 * DVDD	-	DVDD	V	IL = 0.3mA
<b>Serial Communication</b>						
Low-level Input Current	I <sub>IL2</sub>	-10	-	0	μA	V <sub>IL</sub> = GND
High-level Input Current	I <sub>IH2</sub>	0	-	10	μA	At HiZ, V <sub>IH</sub> = DVDD
Low-level Output Voltage	V <sub>OL2</sub>	GND	-	0.2 * DVDD	V	IL = -3mA
<b>Magnetic Sensor</b>						
Moving Range	Rm	-	±300	-	μT	
Measurable Range <sup>(Note 2)</sup>	Ra	-	±1200	-	μT	
X,Y-axis Linearity <sup>(Note 3)</sup>	Lin1	-	0.5	2	%FS	Rm = ±200μT
Z-axis Linearity <sup>(Note 3)</sup>	Lin2	-	1.0	2.8	%FS	Rm = ±200μT
Output Offset	Vofs	-	0	-	LSB	Magnetic Field = 0μT
Magnetic Sensitivity	DeltaV	-	0.042	-	μT/LSB	
Measurement Time	Tms	-	0.5	-	msec	Average 4times

(Note2) Measurable Range: Overall measurable range within which preset operating range can be fit by adjusting appropriate offsets.

(Note3) Linearity [%FS] = Output Error / Rm = (output – ideal output) / Rm

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Typical Performance Curves

(Unless otherwise specified, Ta=25°C, AVDD=1.8V, DVDD=1.8V, GND=0.0V)

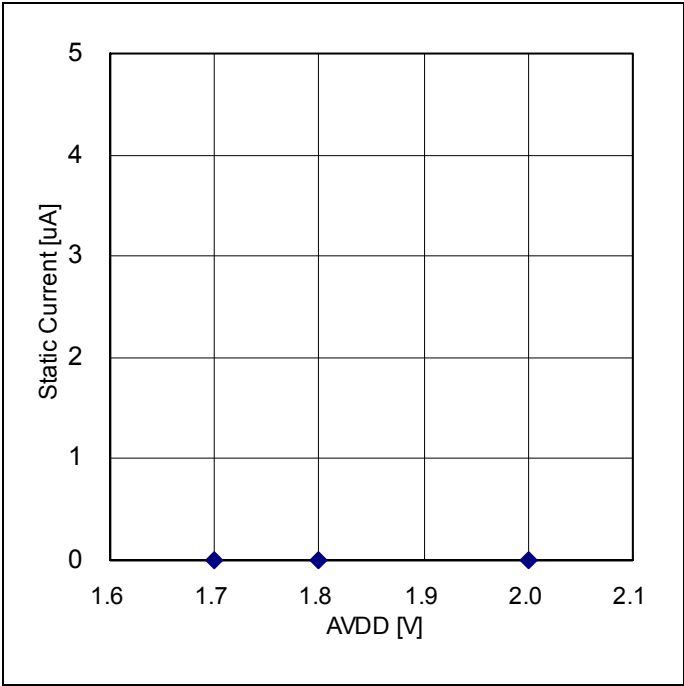


Figure 1. AVDD PowerDown Current Voltage Dependency

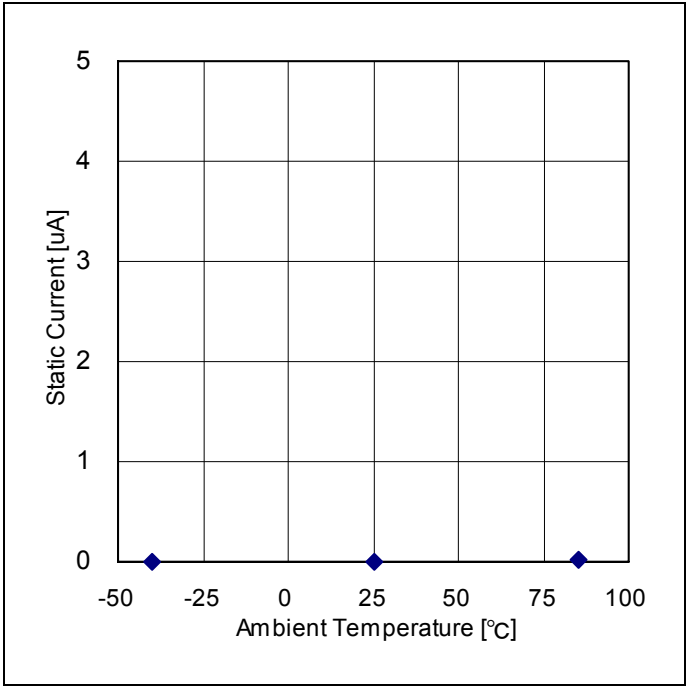


Figure 2. AVDD PowerDown Current Temperature Dependency

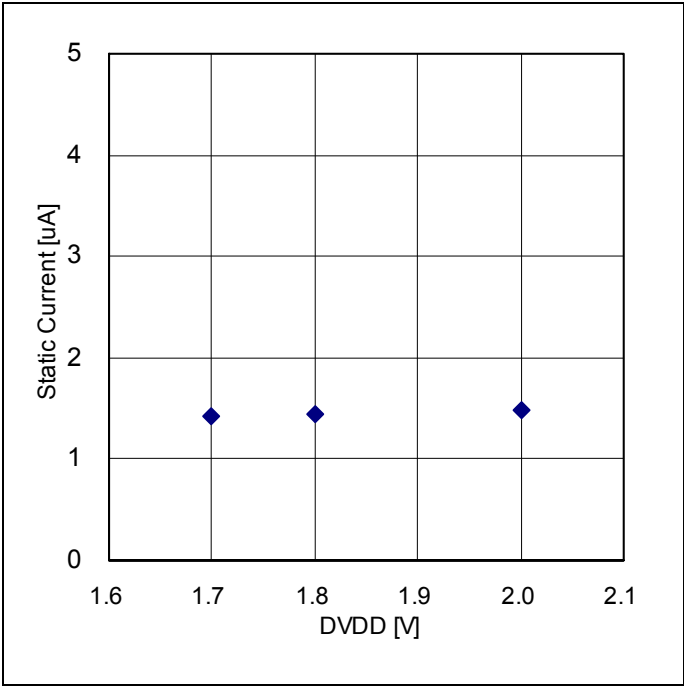


Figure 3. DVDD PowerDown Current Voltage Dependency

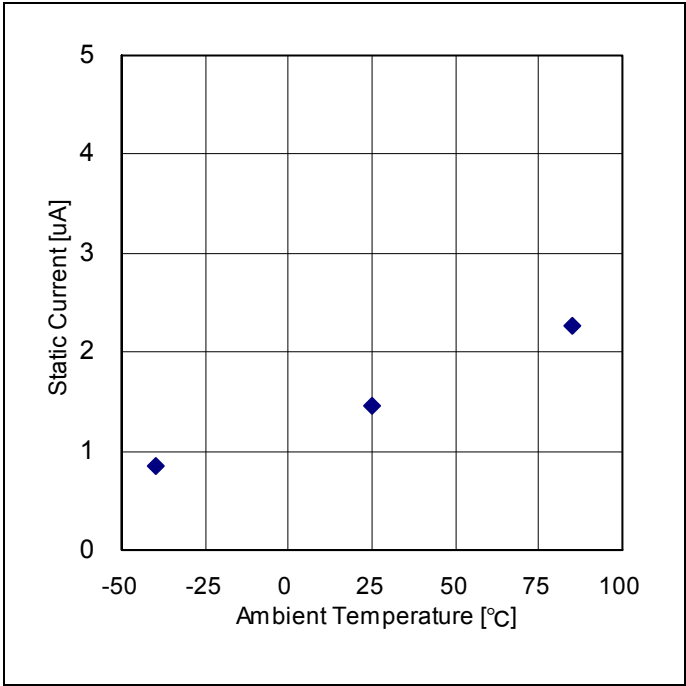


Figure 4. DVDD PowerDown Current Temperature Dependency

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**Typical Performance Curves - continued**

(Unless otherwise specified, Ta=25°C, AVDD=1.8V, DVDD=1.8V, GND=0.0V)

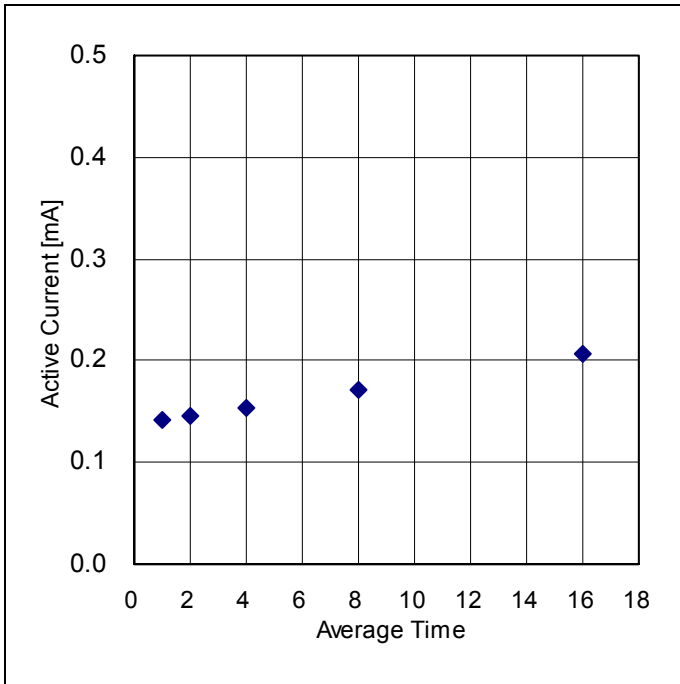


Figure 5. Average Current during Measurement Averaging Dependency (100SPS)

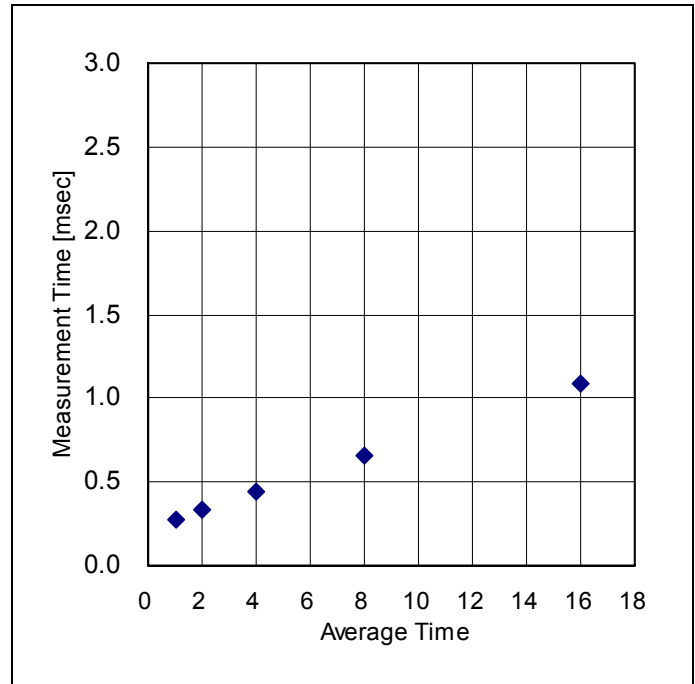


Figure 6. Measurement Time Averaging Dependency

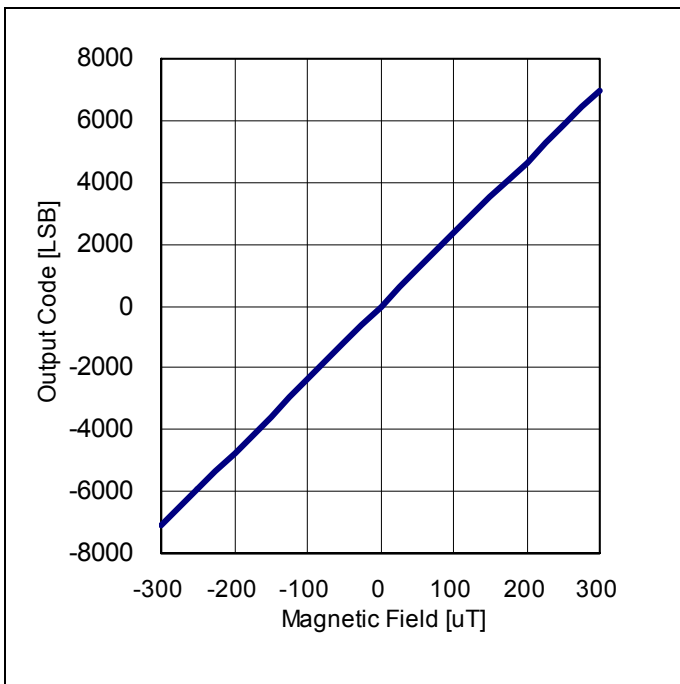


Figure 7. Output Characteristic

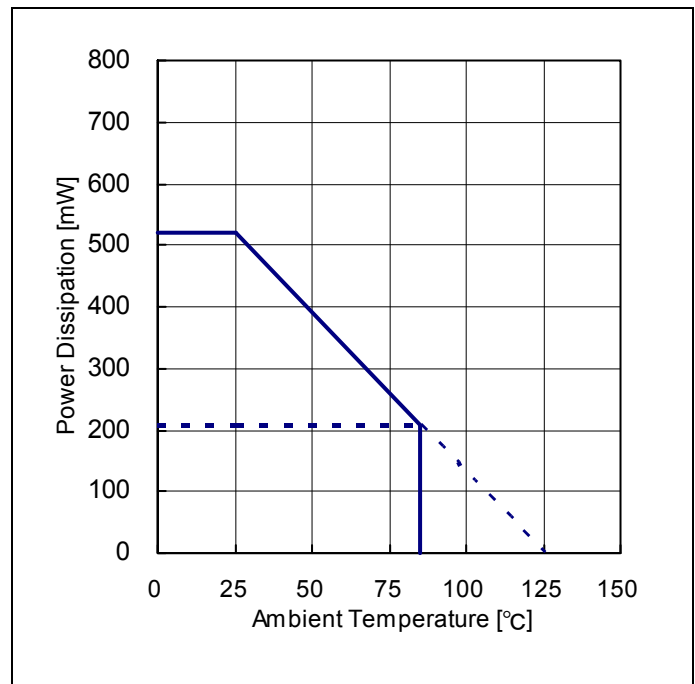
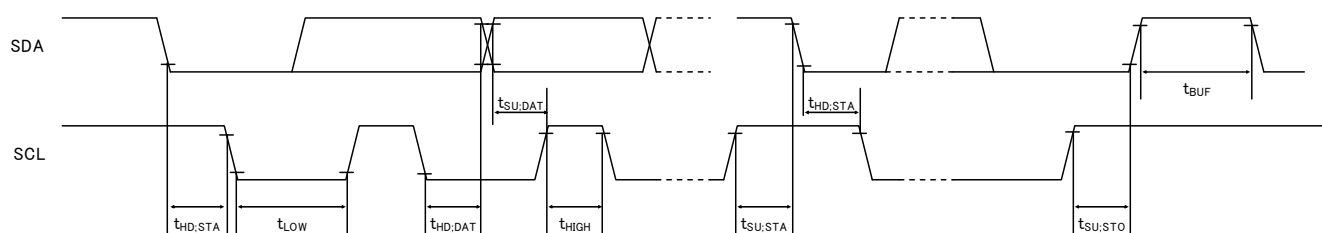


Figure 8. Power Dissipation Curve

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**I<sup>2</sup>C Bus Timing Characteristics** (Unless otherwise specified DVDD = 1.8V, Ta = 25°C)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
I <sup>2</sup> C SCL Clock frequency	$f_{SCL}$	0	—	400	kHz	
I <sup>2</sup> C 'L' Period of the SCL Clock	$t_{LOW}$	1.3	—	—	us	
I <sup>2</sup> C 'H' Period of the SCL Clock	$t_{HIGH}$	0.6	—	—	us	
I <sup>2</sup> C START Condition Setup Time	$t_{SU;STA}$	0.6	—	—	us	
I <sup>2</sup> C Hold Time (repeated) START Condition	$t_{HD;STA}$	0.6	—	—	us	
I <sup>2</sup> C Data Setup Time	$t_{SU;DAT}$	100	—	—	ns	
I <sup>2</sup> C Data Hold Time	$t_{HD;DAT}$	0	—	—	us	
I <sup>2</sup> C Setup Time for STOP Condition	$t_{SU;STO}$	0.6	—	—	us	
I <sup>2</sup> C Bus Free Time between STOP and START Condition	$t_{BUF}$	1.3	—	—	us	

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## Register Map

Name	Address	bit width	R/W	Function
INFO	0x0D/0x0E	16	R	Information (0x0101)
WIA	0x0F	8	R	Who I am (0x41)
DATA_X	0x10/0x11	16	R	X Output value
DATA_Y	0x12/0x13	16	R	Y Output value
DATA_Z	0x14/0x15	16	R	Z Output value
STA1	0x18	8	R	Status1 (DRDY)
CNTL1	0x1B	8	R/W	Control setting 1
CNTL2	0x1C	8	R/W	Control setting 2
CNTL3	0x1D	8	R/W	Control setting 3
PRET	0x30	8	R/W	Preset time
AVE_A	0x40	8	R/W	Average Time setting
CNTL4	0x5C/0x5D	16	R/W	Control setting 4 (LV Reset Release)
TEMP	0x60/0x61	16	R	Temperature value
OFF_X	0x6C/0x6D	16	R/W	Offset X value
OFF_Y	0x72/0x73	16	R/W	Offset Y value
OFF_Z	0x78/0x79	16	R/W	Offset Z value
FINEOUTPUT_X	0x90/0x91	16	R	DATA_X value per OFF_X
FINEOUTPUT_Y	0x92/0x93	16	R	DATA_Y value per OFF_Y
FINEOUTPUT_Z	0x94/0x95	16	R	DATA_Z value per OFF_Z
SENS_X	0x96/0x97	16	R	Sensitivity adjust X value
SENS_Y	0x98/0x99	16	R	Sensitivity adjust Y value
SENS_Z	0x9A/0x9B	16	R	Sensitivity adjust Z value
GAIN_PARA_X	0x9C/0x9D	16	R	Axis interference X value
GAIN_PARA_Y	0x9E/0x9F	16	R	Axis interference Y value
GAIN_PARA_Z	0xA0/0xA1	16	R	Axis interference Z value
OFFZERO_X	0xF8/0xF9	16	R	Offset adjust X value at zero magnetic field
OFFZERO_Y	0xFA/0xFB	16	R	Offset adjust Y value at zero magnetic field
OFFZERO_Z	0xFC/0xFD	16	R	Offset adjust Z value at zero magnetic field

It is the following conditions to be able to access each register.

Condition	Accessible Register
Supply Power	CNTL1 CNTL4 INFO WIA
Supply Power (CNTL1) PC1=1 (CNTL1) RST_LV=0 (CNTL4) RSTB_LV=1	STA1 CNTL2 CNTL3 PRET AVE_A OFF_X,Y,Z
Supply Power (CNTL1) PC1=1 (CNTL1) RST_LV=0 (CNTL4) RSTB_LV=1 (CNTL3) FORCE=1 after first access	DATA_X,Y,Z TEMP FINEOUTPUT_X,Y,Z SENS_X,Y,Z GAIN_PARA_X,Y,Z OFFZERO_X,Y,Z

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## ○ Information Register ( 0x0D/0x0E )

Register	Bit Width	R/W	Address	Description
INFO	16bit	R	0x0D	Information LSB
		R	0x0E	Information MSB

default value 0x0101

## ○ WIA Register ( 0x0F )

Register	Bit Width	R/W	Address	Description
WIA	8bit	R	0x0F	Who I am

default value 0x41

## ○ Output Data Register ( 0x10/0x11, 0x12/0x13, 0x14/0x15 )

Register	Bit Width	R/W	Address	Description
DATAx	16bit	R	0x10	Xch Output value LSB
		R	0x11	Xch Output value MSB
DATAY	16bit	R	0x12	Ych Output value LSB
		R	0x13	Ych Output value MSB
DATAz	16bit	R	0x14	Zch Output value LSB
		R	0x15	Zch Output value MSB

default value 0xFFFF

signed 16bit -2048d(0xF800) to +2047d(0x07FF) [Register OUT\_BIT=0]  
 -8192d(0xE000) to +8191d(0x1FFF) [Register OUT\_BIT=1]

## ○ Status Register ( 0x18 )

Register	Bit Width	R/W	Address	Description
STA1	8bit	R	0x18	Status (DRDY)

default value 0x00

Bit	Name	R/W	Description
7	Reserved	R	Reserved
6	RD_DRDY	R	This bit is output to the DRDY to inform the preparation status of the measured data 0 : Not ready NG 1 : Ready OK
5:0	Reserved	R	Reserved

## ○ Control setting1 Register ( 0x1B )

Register	Bit Width	R/W	Address	Description
CNTL1	8bit	R/W	0x1B	Control setting

default value 0x22

Bit	Name	R/W	Description
7	PC1	R/W	Power Control 0 : PowerDown 1 : Active
6	OUT_BIT	R/W	Output Data bit setting 0 : 12bit Output , 1 : 14bit Output
5	RST_LV	R/W	Logic reset control 0 : Reset release 1 : Reset Reset release at RST_LV(CNTL1)=0 & RSTB_LV(CNTL4)=1
4:3	ODR	R/W	Measurement output data rates 00 : 10Hz , 10 : 20Hz , 01 : 100Hz , 11 : 1kHz
2	Reserved	R/W	Reserved Write "0"
1	FS1	R/W	Measurement mode setting 0 : Continuous mode , 1 : Single mode
0	Reserved	R/W	Reserved Write "0"

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## ○ Control setting2 Register ( 0x1C )

Register	Bit Width	R/W	Address	Description
CNTL2	8bit	R/W	0x1C	Control setting

default value 0x04

Bit	Name	R/W	Description
7:4	Reserved	R/W	Reserved Write "0000"
3	DREN	R/W	DRDY terminal enable setting 0 : Disable , 1 : Enable
2	DRP	R/W	DRDY terminal active setting 0 : Low active , 1 : High active
1:0	Reserved	R/W	Reserved Write "00"

## ○ Control setting3 Register ( 0x1D )

Register	Bit Width	R/W	Address	Description
CNTL3	8bit	R/W	0x1D	Control setting

default value 0x00

Bit	Name	R/W	Description
7	Reserved	R/W	Reserved Write "0"
6	FORCE	R/W	AD start measurement trigger at continuous mode (FS1=0) and single mode (FS1=1) 1: Start measurement ※Register is automatic clear "0" after write data "1" ※Write data "0" is invalid ※If write data "1" on measurement way, restart measurement
5:0	Reserved	R/W	Reserved Write "00000"

## ○ Preset time Register ( 0x30 )

Register	Bit Width	R/W	Address	Description
PRET	8bit	R/W	0x30	Preset time

default value 0x00

Bit	Name	R/W	Description
7:1	Reserved	R/W	Reserved Write "0000000"
0	PS	R/W	- Write "0"

## ○ Average time Register ( 0x40 )

Register	Bit Width	R/W	Address	Description
AVE_A	8bit	R/W	0x40	Average Time setting

default value 0x00

Bit	Name	R/W	Description
7:5	Reserved	R/W	Reserved Write "000"
4:2	AVE_A	R/W	Average Time 000:4times, 001:1times, 010:2times 011:8times, 100:16times
1:0	Reserved	R/W	Reserved Write "00"

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## ○ Control setting4 Register ( 0x5C/0x5D )

Register	Bit Width	R/W	Address	Description
CNTL4	16bit	R/W	0x5C	Control setting LSB
		R/W	0x5D	Control setting MSB

default value 0x00

Bit	Name	R/W	Description
(0x5C) 7:0	Reserved	R/W	Reserved (ignore write data)
(0x5D) 7:0	RSTB_LV	R/W	RSTB_LV=1 by write access (ignore write data) Reset release at RST_LV(CNTL1)=0 & RSTB_LV(CNTL4)=1 RSTB_LV=0 by write PC1(CNTL1)=0

## ○ Temperature value Register ( 0x60/0x61 )

Register	Bit Width	R/W	Address	Description
TEMP	16bit	R	0x60	Temperature value LSB
		R	0x61	Temperature value MSB

default value 0xFFFF

unsigned 16bit 0d(0x0000) to +4095d(0x0FFF) [Register OUT\_BIT=0]  
 0d(0x0000) to +16383d(0x3FFF) [Register OUT\_BIT=1]

## ○ Offset value Register ( 0x6C/0x6D, 0x72/0x73, 0x78/0x79 )

Register	Bit Width	R/W	Address	Description
OFF_X	16bit	R/W	0x6C	Xch Offset value
		R/W	0x6D	Reserved Write "00000000"
OFF_Y	16bit	R/W	0x72	Ych Offset value
		R/W	0x73	Reserved Write "00000000"
OFF_Z	16bit	R/W	0x78	Zch Offset value
		R/W	0x79	Reserved Write "00000000"

default value 0x30

unsigned 8bit 0d(0x00) to +95d(0x5F)

## ○ Fine output Register ( 0x90/0x91, 0x92/0x93, 0x94/0x95 )

Register	Bit Width	R/W	Address	Description
FINEOUTPUTX	16bit	R	0x90	DATA_X value per OFF_X LSB
		R	0x91	DATA_X value per OFF_X MSB
FINEOUTPUTY	16bit	R	0x92	DATA_Y value per OFF_Y LSB
		R	0x93	DATA_Y value per OFF_Y MSB
FINEOUTPUTZ	16bit	R	0x94	DATA_Z value per OFF_Z LSB
		R	0x95	DATA_Z value per OFF_Z MSB

default value 0xFFFF

unsigned 16bit 0d(0x0000) to +16383d(0x3FFF)

## ○ Sensitivity Register ( 0x96/0x97, 0x98/0x99, 0x9A/0x9B )

Register	Bit Width	R/W	Address	Description
SENSX	16bit	R	0x96	Reserved
		R	0x97	Reserved
SENSY	16bit	R	0x98	Reserved
		R	0x99	Reserved
SENSZ	16bit	R	0x9A	Reserved
		R	0x9B	Reserved

default value 0xFF

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## ○ Axis interference Register ( 0x9C/0x9D, 0x9E/0x9F, 0xA0/0xA1 )

Register	Bit Width	R/W	Address	Description
GAIN_PARA_X	16bit	R	0x9C	Axis interference Xch to Zch
		R	0x9D	Axis interference Xch to Ych
GAIN_PARA_Y	16bit	R	0x9E	Axis interference Ych to Zch
		R	0x9F	Axis interference Ych to Xch
GAIN_PARA_Z	16bit	R	0xA0	Axis interference Zch to Ych
		R	0xA1	Axis interference Zch to Xch

default value 0xXX

unsigned 8bit 0d(0x00) to +255d(0xFF)

## ○ Offset at zero magnetic field Register ( 0xF8/0xF9, 0xFA/0xFB, 0xFC/0xFD )

Register	Bit Width	R/W	Address	Description
OFFZEROX	16bit	R	0xF8	Reserved
		R	0xF9	Reserved
OFFZEROY	16bit	R	0xFA	Reserved
		R	0xFB	Reserved
OFFZEROZ	16bit	R	0xFC	Reserved
		R	0xFD	Reserved

default value 0xXX

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I<sup>2</sup>C Bus Format

1. Slave address : "0001110" (ADDR=L) or "0001111" (ADDR=H)
2. Write format

(1) Case of indicating register address

ST	Slave Address	W 0	ACK	Indicate register address	ACK	SP
----	---------------	--------	-----	---------------------------	-----	----

(2) Case of writing data register after indicating register address

ST	Slave Address	W 0	ACK	Indicate register address	ACK	
Data specified at register address field	ACK	.....	ACK	Data specified at register address field + N	ACK	SP


3. Read format


(1) Case of reading data after indicating register address

ST	Slave Address	W 0	ACK	Indicate register address	ACK	
ST	Slave Address	R 1	ACK	Data specified at register address field	ACK	
Data specified at register address field + 1	ACK	.....	ACK	Data specified at register address field + N	NACK	SP

(2) Case of reading data

ST	Slave Address	R 1	ACK	Data specified at register address field	ACK	
Data specified at register address field + 1	ACK	.....	ACK	Data specified at register address field + N	NACK	SP

 from master to slave

 from slave to master

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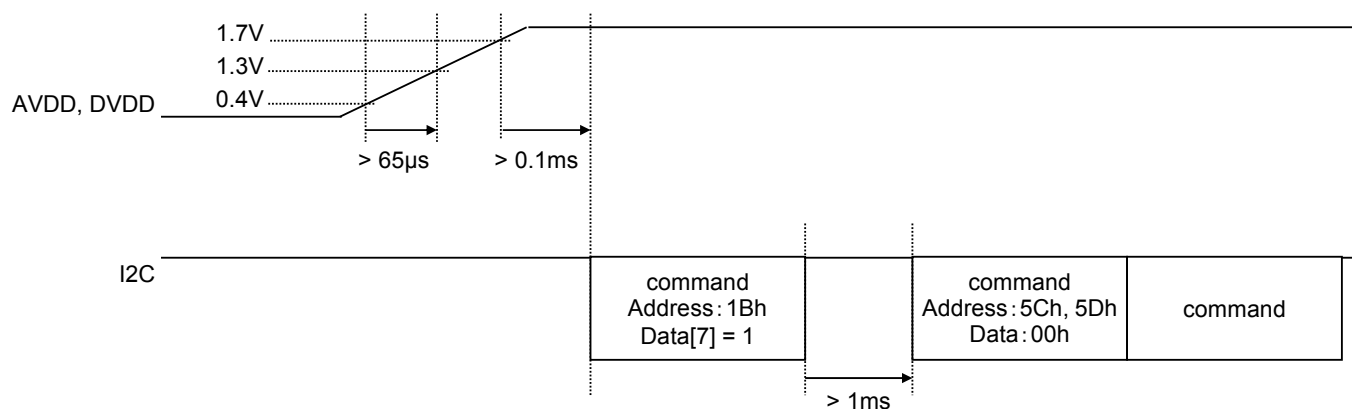
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## Control Sequence

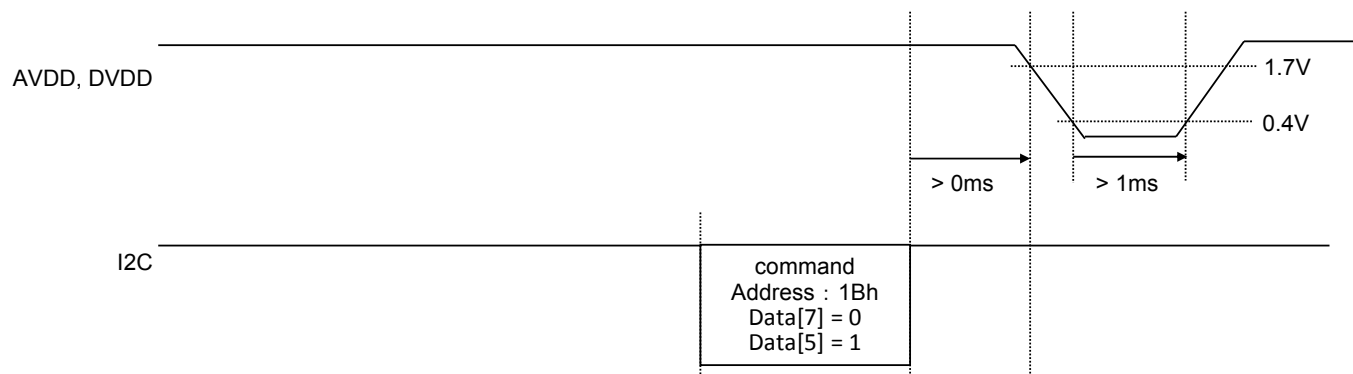
## 1. Control Sequence

## 1.1 Power supply start-up sequence

The order of starting up the power supplies of AVDD and DVDD is arbitrary, when they are supplied from different sources. Please do the command control by I<sup>2</sup>C after all powers are supplied.

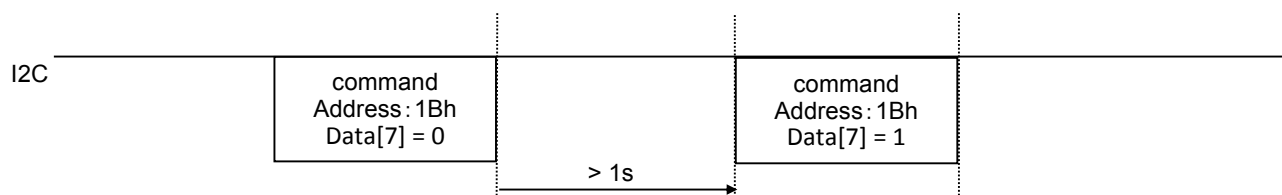


## 1.2 Power supply end sequence



## 1.3 POWER\_DOWN control

When removing PowerDown mode(address : 1Bh CNTL1\_PC1=1) after setting to PowerDown mode(address : 1Bh CNTL1\_PC1=0), please keep PowerDown state more than 1S like below figure.



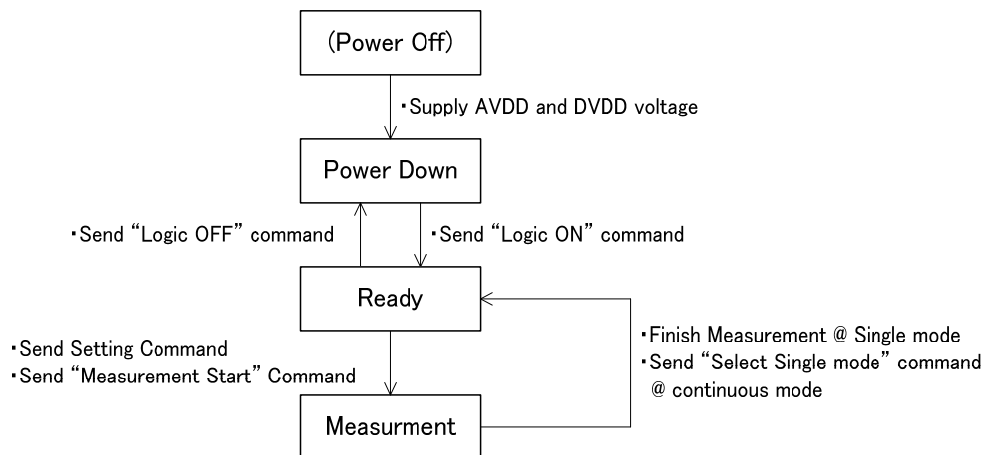
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## 2. Measurement sequence

There are the following two kinds of measurement modes

Continuous Mode	BM1422GMV is measured at specified cycle (ODR=10,20,100,1kHz) at the cycle.
Single Mode	BM1422GMV is measured by the measurement request from the host.



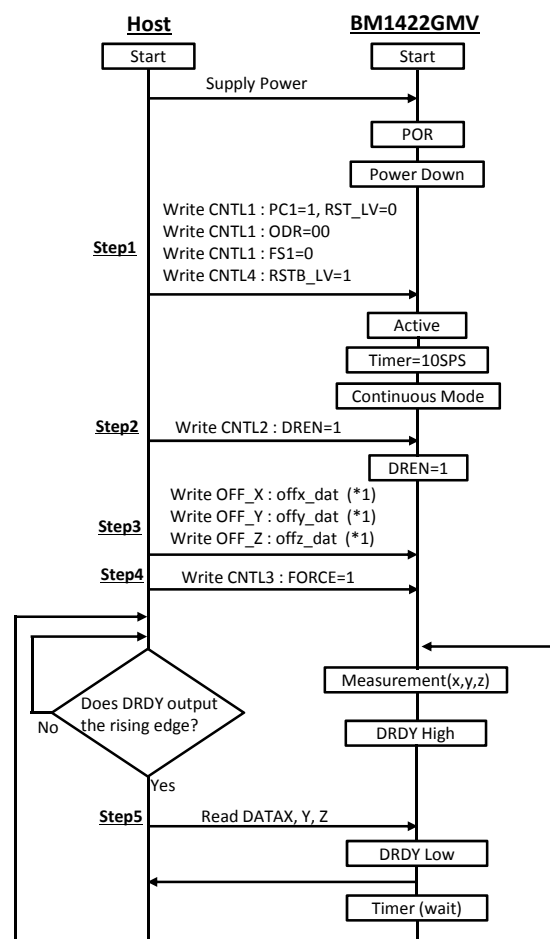
## 2.1 Continuous Mode

(Send command example) Case of 12bit Output Data

	Register Name	Address	Data
Step1	CNTL1	0x1B	0x80
	CNTL4	0x5C	0x00
		0x5D	0x00
Step2	CNTL2	0x1C	0x08
Step3	OFF_X	0x6C	offx_dat
	OFF_Y	0x72	offy_dat
	OFF_Z	0x78	offz_dat
Step4	CNTL3	0x1D	0x40
Step5	DATAX	0x10	Read
		0x11	
	DATAZ	0x12	Read
		0x13	
	DATAZ	0x14	Read
		0x15	

(Send command example) Case of 14bit Output Data

	Register Name	Address	Data
Step1	CNTL1	0x1B	0xC0
	CNTL4	0x5C	0x00
		0x5D	0x00
Step2	CNTL2	0x1C	0x08
Step3	OFF_X	0x6C	offx_dat
	OFF_Y	0x72	offy_dat
	OFF_Z	0x78	offz_dat
Step4	CNTL3	0x1D	0x40
Step5	DATAX	0x10	Read
		0x11	
	DATAZ	0x12	Read
		0x13	
	DATAZ	0x14	Read
		0x15	



(\*1) The value is obtained at offset adjustment.  
If not obtained yet, then skip.

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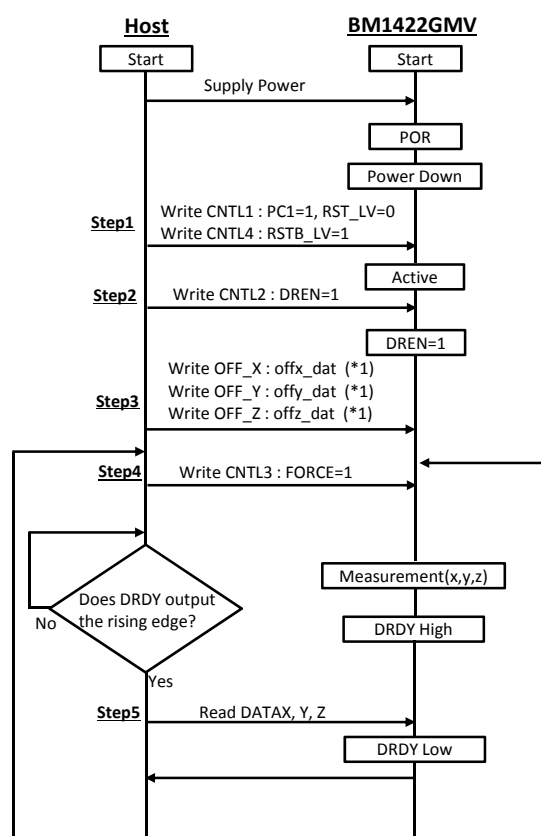
## 2.2 Single Mode

(Send command example) Case of 12bit Output Data

	Register Name	Address	Data
Step1	CNTL1	0x1B	0x82
	CNTL4	0x5C 0x5D	0x00
Step2	CNTL2	0x1C	0x08
Step3	OFF_X	0x6C	offx_dat
	OFF_Y	0x72	offy_dat
	OFF_Z	0x78	offz_dat
Step4	CNTL3	0x1D	0x40
Step5	DATAX	0x10	Read
		0x11	
	DATAY	0x12	Read
		0x13	
	DATAZ	0x14 0x15	Read

(Send command example) Case of 14bit Output Data

	Register Name	Address	Data
Step1	CNTL1	0x1B	0xC2
	CNTL4	0x5C 0x5D	0x00
Step2	CNTL2	0x1C	0x08
Step3	OFF_X	0x6C	offx_dat
	OFF_Y	0x72	offy_dat
	OFF_Z	0x78	offz_dat
Step4	CNTL3	0x1D	0x40
Step5	DATAX	0x10	Read
		0x11	
	DATAY	0x12	Read
		0x13	
	DATAZ	0x14 0x15	Read



(\*1) The value is obtained at offset adjustment.  
If not obtained yet, then skip.

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## 3. Offset Adjustment

Offset adjustment sequence make the output value around zero under the normal magnetic environment.

After measuring the following parameter, HOST should save it in memory, and it needs to be set after applying power supply to BM1422GMV.

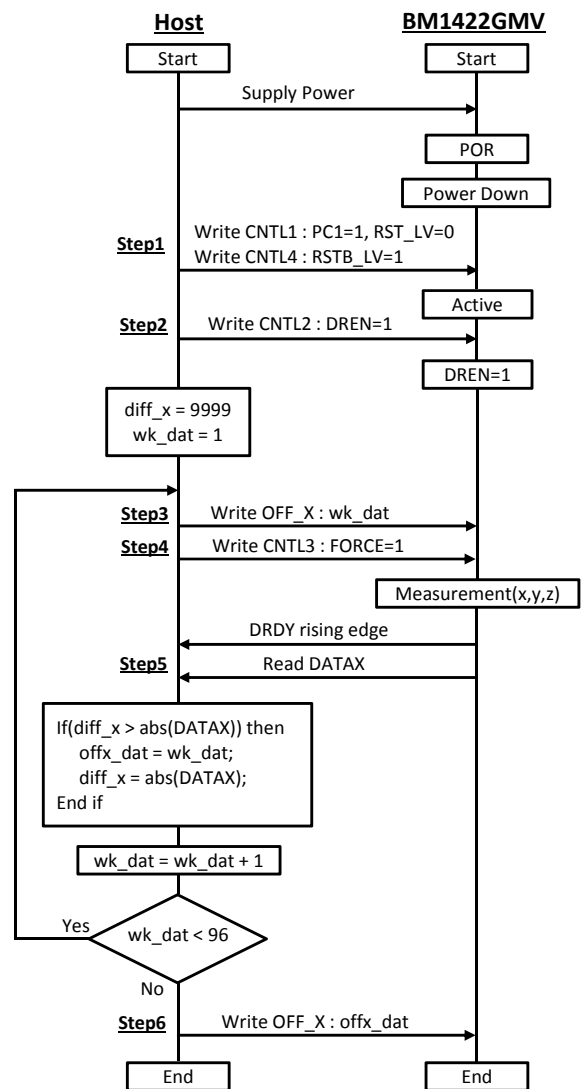
Parameter	Description
offx_dat	Adjusted value of Xch offset
offy_dat	Adjusted value of Ych offset
offz_dat	Adjusted value of Zch offset

(Send command example) Case of 12bit Output Data

	Register Name	Address	Data
Step1	CNTL1	0x1B	0x82
	CNTL4	0x5C	0x00
		0x5D	0x00
Step2	CNTL2	0x1C	0x08
Step3	OFF_X	0x6C	wk_dat
Step4	CNTL3	0x1D	0x40
Step5	DATA_X	0x10	Read
		0x11	
Step6	OFF_X	0x6C	offx_dat

(Send command example) Case of 14bit Output Data

	Register Name	Address	Data
Step1	CNTL1	0x1B	0xC2
	CNTL4	0x5C	0x00
		0x5D	0x00
Step2	CNTL2	0x1C	0x08
Step3	OFF_X	0x6C	wk_dat
Step4	CNTL3	0x1D	0x40
Step5	DATA_X	0x10	Read
		0x11	
Step6	OFF_X	0x6C	offx_dat



Write only Xch offset adjustment  
Ych and Zch should also be performed

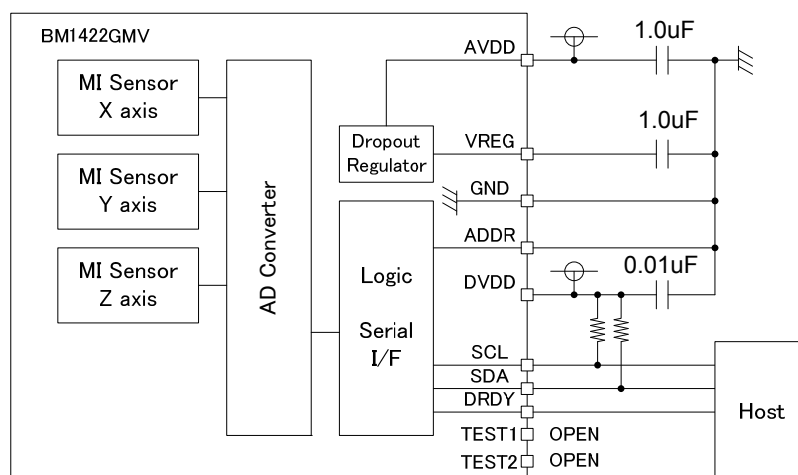
When OFF\_X, OFF\_Y, OFF\_Z are changed in the same magnetic field environment, the change directions of the output are as follows

	OFF_X,Y,Z +	OFF_X,Y,Z -
X axis	-	+
Y axis	-	+
Z axis	-	+

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## Application Example



(Note) Sensor property may change due to around magnetic parts. We recommend calibrating the sensitivity and origin point of magnetic sensors after mounting.

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I/O equivalent circuit

Pin name	Equivalent Circuit Diagram	Pin name	Equivalent Circuit Diagram
SCL		SDA	
DRDY		ADDR	
TEST1		TEST2	
VREG			

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## Operational Notes

### 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

### 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

### 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

### 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

### 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

### 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

### 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

### 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

### 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

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**Operational Notes – continued****10. Inter-pin Short and Mounting Errors**

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

**11. Unused Input Pins**

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

**12. Regarding the Input Pin of the IC**

In the construction of this IC, P-N junctions are inevitably formed creating parasitic diodes or transistors. The operation of these parasitic elements can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions which cause these parasitic elements to operate, such as applying a voltage to an input pin lower than the ground voltage should be avoided. Furthermore, do not apply a voltage to the input pins when no power supply voltage is applied to the IC. Even if the power supply voltage is applied, make sure that the input pins have voltages within the values specified in the electrical characteristics of this IC.

**13. Ceramic Capacitor**

When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

**14. Absolute Maximum Ratings**

Operate the IC such that the output voltage, output current, and power dissipation are all within the Absolute Maximum Ratings.

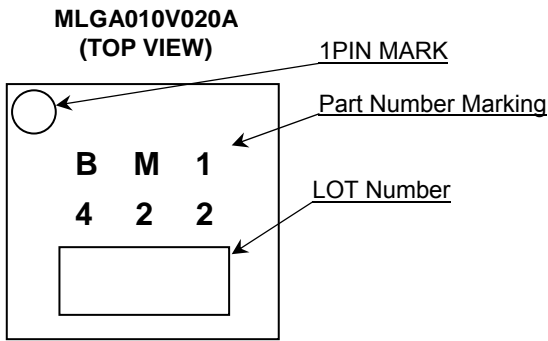
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Ordering Information

B M 1 4 2 2 G M V									-	Z E 2		
Part Number									Package	Packaging and forming specification		
									GMV:MLGA010V020A	E2: Embossed tape and reel		

Marking Diagrams

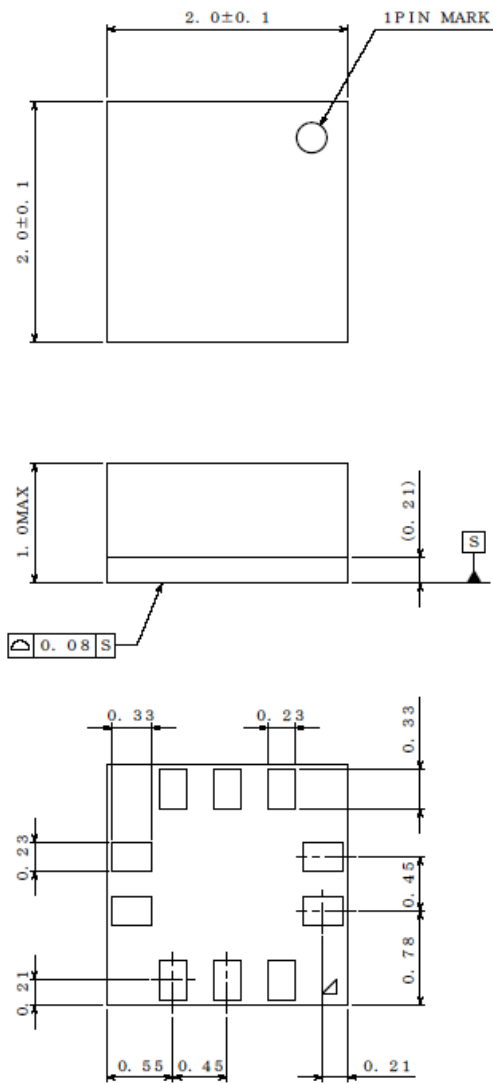


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Physical Dimension, Tape and Reel Information

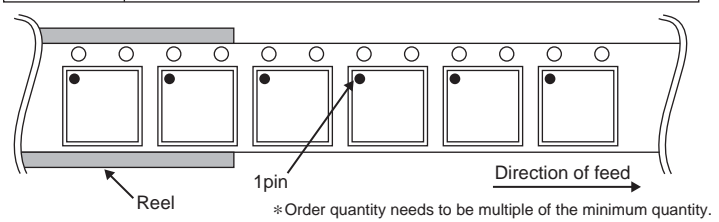
Package Name	MLGA010V020A
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(UNIT : mm)

<Tape and Reel information>

Tape	Embossed carrier tape (with dry pack)
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



\* Order quantity needs to be multiple of the minimum quantity.

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## Revision History

Date	Revision	Changes
01.Nov.2013	001	New Release
25.Dec.2013	002	Change Figure of Start-up sequence.
5.Feb.2014	003	Change Package name, Change Physical Dimension
13.Feb.2014	004	Add Register Map and Operational Notes
26.Feb.2014	005	Add Block Diagram, Register Description, Measurement Sequence, Application Example, I/O equivalence circuit
4.Mar.2014	006	Correction of errors
8.Apr.2014	007	Correction of errors
16.Apr.2014	008	Correction of errors
14.May.2014	009	Correction of errors, Add average time register
18.Jun.2014	010	Add OUT_BIT Register at CNTL1, Change Linearity Spec
12.Nov.2014	011	Add Register access condition, Add Description of OFF_X,Y,Z
10.Dec.2014	012	Correction of errors
30.Jan.2015	013	Change Control Sequence
16.Feb.2015	014	Change Input Voltage Range, Add Contents, Add Typical Performance Curves
24.Feb.2015	015	Change Typical Performance Curves

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - Installation of protection circuits or other protective devices to improve system safety
  - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

## Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

## Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

## Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

## Precaution for Product Label

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